

### **Product Description**

### Modified epoxy | 1 part | solvent-free | heat-curing

- Glob top
- Fill for "Frame and Fill"
- Electrics
- Electronics

- Very good flowability
- High glass transition temperature
- No bleeding
- Very low ionic content (<10ppm)</li>
- Suitable for semiconductors

#### **Curing Properties**

This adhesive must be cured with heat. Typical curing temperatures are listed in the table below.

Temperatures	Time
30min at 120°C and afterwards 45min at 150°C	
Alternative 150°C	1h

The heat cure times are only provided as a guideline. They are derived from curing a 2g adhesive sample without affixed substrates in a laboratory environment. Actual cure times can vary based on part size, configuration, adhesive volume, temperature control, and the time required for the component substrates to attain oven temperature.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.

Technical Data		
Resin	Ероху	
Appearance	Black	
Filler	Quartz	
Filler - weight [%]	50	
Particle size D95 [µm]	40	



Viscosity [mPas] (Kinexus Rheometer, 25 °C, 5s <sup>-1</sup> )         3,000 - 8,000           PE-Norm 064         1.0 - 1.3           Density [g/cm³]         1.4 - 1.6           PE-Norm 004         >100           PE-Norm 050         >100           Working life [days]         3           @ room temperature         3           Cured Material         100           Hardness shore D         70 - 90           PE-Norm 006         70 - 90           Temperature resistance [°C]         -40 - 200           PE-Norm 059         -40 - 200           Shrinkage [%]         <1           Vater absorption [%]         <1           PE-Norm 031         <1           Water absorption [%]         <1           PE-Norm 016         <1           Coefficient of thermal expansion [ppm/K] below Tg         <40           PE-Norm 017         100 - 150           Dielectric constant [10kHz]         1 - 3           Dielectric constant [10kHz]         1 - 3           Dielectric strength [kV/mm]         18 - 22	Uncured Material	
PE-Norm 064       1.0 - 1.3         Thixotropic index [1/10]       1.0 - 1.3         Density [g/cm³]       1.4 - 1.6         FL-Norm 004       >100         Flash point [°C]       >100         Working life [days]       3         @ room temperature       3         Cured Material       70 - 90         Hardness shore D       70 - 90         PE-Norm 056       70 - 90         Shrinkage [%]       -40 - 200         PE-Norm 059       -40 - 200         Shrinkage [%]       <1	Viscosity [mPas] (Kinexus Rheometer, 25 °C, 5s <sup>-1</sup> )	3 000 - 8 000
PE-Norm 0641.0 - 1.3Density [g/cm³]1.4 - 1.6PE-Norm 0041.4 - 1.6PE-Norm 050>100Working life [days]3@ room temperature3Cured Material70 - 90Hardness shore D70 - 90PE-Norm 00670 - 90Shrinkage [%]-40 - 200Shrinkage [%]<1		3,000 0,000
PE-Norm 064         Density [g/cm³]         PE-Norm 004         Flash point [°C]         PE-Norm 050         Working life [days]         @ room temperature         3         @ room temperature         1         Hardness shore D         PE-Norm 006         Temperature resistance [°C]         PE-Norm 005         Shrinkage [%]         PE-Norm 031         Water absorption [%]         PE-Norm 016         Glass transition temperature - DSC [°C]         PE-Norm 017         Coefficient of thermal expansion [ppm/K] below Tg         PE-Norm 017         Dielectric constant [10kHz]         1ec 62631-2-1         Dielectric strength [kV/mm]         DIN EN 60243         Young's modulus – Tensile test [MPa]         150°C, 60min         PE-Norm 056         Tensile strength [MPa]		1.0 - 1.3
PE-Norm 0041.4 - 1.6Flash point [°C] PE-Norm 050>100Working life [days] @ room temperature3Cured Material1Hardness shore D PE-Norm 00670 - 90Temperature resistance [°C] PE-Norm 059-40 - 200Shrinkage [%] PE-Norm 031<1		
Flash point [°C]       >100         PE-Norm 050       3         @ room temperature       3         Cured Material       70 – 90         Hardness shore D       70 – 90         PE-Norm 006       70 – 90         Shrinkage [%]       -40 – 200         PE-Norm 059       -40 – 200         Shrinkage [%]       <1		1.4 – 1.6
PE-Norm 050       \$100         Working life [days]       3         @ room temperature       3         Cured Material       70 – 90         Hardness shore D       70 – 90         PE-Norm 006       -40 – 200         Shrinkage [%]       -40 – 200         PE-Norm 059       -40 – 200         Shrinkage [%]       <1		
Working life [days] @ room temperature3Cured Material Hardness shore D PE-Norm 00670 - 90Temperature resistance [°C] PE-Norm 059-40 - 200Shrinkage [%] PE-Norm 031<1		>100
@ room temperature       3         Cured Material       1         Hardness shore D       70 – 90         PE-Norm 006       70 – 90         Temperature resistance [°C]       -40 – 200         PE-Norm 059       -40 – 200         Shrinkage [%]       <1		
Cured MaterialHardness shore DPE-Norm 006Temperature resistance [°C]PE-Norm 059Shrinkage [%]PE-Norm 031Water absorption [%]PE-Norm 016Glass transition temperature - DSC [°C]PE-Norm 009Coefficient of thermal expansion [ppm/K] below TgPE-Norm 017Coefficient of thermal expansion [ppm/K] above TgPE-Norm 017Dielectric constant [10kHz]IEC 62631-2-1Dielectric strength [kV/mm]Dielectric strength [kV/mm]J18 - 22Young's modulus – Tensile test [MPa]150°C, 60minPE-Norm 056Tensile strength [MPa]		3
Hardness shore D PE-Norm 00670 - 90Temperature resistance [°C] PE-Norm 059-40 - 200Shrinkage [%] PE-Norm 031<1		
PE-Norm 00670-90Temperature resistance [°C] PE-Norm 059-40-200Shrinkage [%] PE-Norm 031<1	Cured Material	
PE-Norm 006Temperature resistance [°C]PE-Norm 059Shrinkage [%]PE-Norm 031Water absorption [%]PE-Norm 016Glass transition temperature - DSC [°C]PE-Norm 009Coefficient of thermal expansion [ppm/K] below TgPE-Norm 017Coefficient of thermal expansion [ppm/K] above TgPE-Norm 017Dielectric constant [10kHz]IEC 62631-2-1Dielectric strength [kV/mm]Dielectric strength [kV/mm]18 - 22Young's modulus – Tensile test [MPa]150°C, 60minPE-Norm 056Tensile strength [MPa]	Hardness shore D	70 – 90
PE-Norm 059-40 - 200Shrinkage [%] PE-Norm 031<1		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
PE-Norm 059Shrinkage [%] PE-Norm 031<1	• • •	-40 - 200
PE-Norm 031<1Water absorption [%] PE-Norm 016<1		
Water absorption [%] PE-Norm 016<1Glass transition temperature - DSC [°C] PE-Norm 009150 - 180Coefficient of thermal expansion [ppm/K] below Tg PE-Norm 017<40	• • •	<1
PE-Norm 016<1Glass transition temperature - DSC [°C] PE-Norm 009150 - 180Coefficient of thermal expansion [ppm/K] below Tg PE-Norm 017<40		
Glass transition temperature - DSC [°C] PE-Norm 009150 - 180Coefficient of thermal expansion [ppm/K] below Tg PE-Norm 017<40		<1
PE-Norm 009130 = 130Coefficient of thermal expansion [ppm/K] below Tg PE-Norm 017<40	PE-Norm 016	
PE-Norm 009Coefficient of thermal expansion [ppm/K] below TgPE-Norm 017Coefficient of thermal expansion [ppm/K] above TgPE-Norm 017Dielectric constant [10kHz]1-3Dielectric strength [kV/mm]DIN EN 60243Young's modulus – Tensile test [MPa]150°C, 60minPE-Norm 056Tensile strength [MPa]	Glass transition temperature - DSC [°C]	150 - 180
PE-Norm 017Coefficient of thermal expansion [ppm/K] above Tg PE-Norm 017100 – 150Dielectric constant [10kHz] IEC 62631-2-11 – 3Dielectric strength [kV/mm] DIN EN 6024318 - 22Young's modulus – Tensile test [MPa] 150°C, 60min PE-Norm 056700 – 850Tensile strength [MPa]100 – 100	PE-Norm 009	130 180
PE-Norm 017Coefficient of thermal expansion [ppm/K] above Tg PE-Norm 017Dielectric constant [10kHz] IEC 62631-2-1Dielectric strength [kV/mm] DIN EN 60243Young's modulus – Tensile test [MPa] 150°C, 60min PE-Norm 056Tensile strength [MPa]	Coefficient of thermal expansion [ppm/K] below Tg	<40
PE-Norm 017         IOU – 130           Dielectric constant [10kHz]         1 – 3           IEC 62631-2-1         1 – 3           Dielectric strength [kV/mm]         18 - 22           JIN EN 60243         180 – 100           Young's modulus – Tensile test [MPa]         700 – 850           PE-Norm 056         Tensile strength [MPa]		
PE-Norm 017         Dielectric constant [10kHz]         IEC 62631-2-1         Dielectric strength [kV/mm]         DIN EN 60243         Young's modulus – Tensile test [MPa]         150°C, 60min         PE-Norm 056         Tensile strength [MPa]		100 – 150
IEC 62631-2-1I - 3Dielectric strength [kV/mm]18 - 22DIN EN 6024318 - 22Young's modulus – Tensile test [MPa]700 - 850PE-Norm 056700 - 850Tensile strength [MPa]100 - 850	PE-Norm 017	
IEC 62631-2-1I - 3Dielectric strength [kV/mm]18 - 22DIN EN 6024318 - 22Young's modulus – Tensile test [MPa]700 - 850PE-Norm 056700 - 850Tensile strength [MPa]100 - 850	Dielectric constant [10kHz]	
DIN EN 60243     18 - 22       Young's modulus – Tensile test [MPa]     700 - 850       150°C, 60min     700 - 850       PE-Norm 056     700 - 850		1-3
DIN EN 60243         Young's modulus – Tensile test [MPa]         150°C, 60min         PE-Norm 056         Tensile strength [MPa]	Dielectric strength [kV/mm]	10 22
150°C, 60min         700 – 850           PE-Norm 056         Tensile strength [MPa]	DIN EN 60243	10 - 22
150°C, 60min         700 – 850           PE-Norm 056         Tensile strength [MPa]	Young's modulus Tansila tast [MDa]	
PE-Norm 056 Tensile strength [MPa]		700 - 850
Tensile strength [MPa]		,00 - 850
150°C, 60min 24 – 30	• • •	24 – 30
PE-Norm 014		2+ 30
Elongation at break [%]		
150°C, 60min <1		<1
PE-Norm 014		



### Transport/Storage/Shelf Life

Package type	Transport	Storage	Shelf life*
Syringe/Cartridge	-20°C	-20°C	At delivery
Other packages		-20 C	max. 3 months

\*Store in original, unopened containers!

#### Instructions for use

#### Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP<sup>®</sup> from Panacol, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

#### Application

Our products are supplied ready to use. Depending on packaging they can be applied by hand directly from the container or by using compatible dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. To obtain best results, the adhesive and substrates to be bonded may not be cold and should be allowed to warm to room temperature prior to processing. For safety information refer to our Material Safety Data Sheet (MSDS).

#### Storage

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Panacol cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

#### Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!



#### Disclaimer

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

### THE VALUES NOTED IN THIS TECHNICAL DATA SHEET ARE TYPICAL PROPERTIES AND ARE NOT MEANT TO BE USED AS PRODUCT SPECIFICATIONS.

The information contained in this data sheet is believed to be accurate and is provided for information only. Panacol makes no representation or warranties of any kind concerning this information. It is the user's responsibility to determine the suitability of this product for any intended use. Panacol does not assume responsibility for test or performance results obtained by the user. The user assumes all risk and liability connected with the use of this product.

The user should adopt such precautions and use guidelines as may be advisable for the protection of property and persons against any hazards that may be involved in this product's handling or use. Panacol specifically disclaims any liability for consequential or incidental damages of any kind arising from the handling or use of this product. The information contained in this Technical Data Sheet offers no assurance that the product use, application, or process will not infringe on existing patents or licenses of others. Nothing in this Technical Data Sheet transfers or grants license for the use of any patents, trade secrets, intellectual property, or confidential information that is the property of Panacol.

Except as otherwise noted, all trademarks in this document (identified as \*) are the property of Panacol.

Contact

Panacol-Elosol GmbH Stierstädter Straße 4 61449 Steinbach Germany Phone: +49 6171 6202-0 Mail: info@panacol.de www.panacol.com

Panacol-USA. Inc. 142 Industrial Lane Torrington CT 06790 USA Phone: +1 860-738-7449 Mail: info@panacol-usa.com www.panacol-usa.com

Panacol-Korea Co., Ltd. #707, Kranz Techno, 388 Dunchon-daero Junwon-gu, Seongnam Gyeonggi-do, 13403 KOREA Phone: +82 31 749 1701 Mail: info@panacol-korea.com www.eleco-panacol.fr www.panacol-korea.com

Eleco Panacol – EFD 125, av Louis Roche Z.A. des Basses Noëls 92238 Gennevilliers Cdx FRANCE Tél.: +33 (0)1 47 92 41 80 Mail: eleco@eleco-panacol.fr

> Page 4/4 Updated 11.04.2024 Revision: 1 **DIN ISO 9001 certified**